

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Kimio TSUNEMASU et al

Date: June 1, 2001

Serial No.:

Group Art Unit:

Filed:

Examiner:

For: MOUNTING STRUCTURE OF SEMICONDUCTOR PACKAGE

Asst. Commissioner for Patents

Washington, D.C. 20231

AMENDMENT/SUBMISSION

Prior to examination, please amend the application as follows.

FEE CALCULATION

Any additional fee required has been calculated as follows:

_____ If checked, "Small Entity" status is claimed.

	NO. CLAIMS		HIGHEST NO.				RATE	ADDIT.
	AFTER	AMENDMENT	PREVIOUSLY	PAID FOR	EXTRA PRESENT			
TOTAL	10	MINUS	20	* =	0	X	(\$9 SE or \$18)	\$
INDEP.	1	MINUS	3	** =	0	X	(\$40 SE or \$80)	\$
FIRST PRESENTATION OF MULTIPLE DEPENDENT CLAIM						X	(\$135 SE or \$270)	\$
								TOTAL \$ -----

* not less than 20 ** not less than 3

If any additional payment is required, a check which includes the calculated fee of \$ _____ (OFGS Check No. _____) is attached.

In the event the actual fee is greater than the payment submitted or is inadvertently not enclosed or if any additional fee during the prosecution of this application is not paid, the Patent Office is authorized to charge the underpayment to Deposit Account No. 15-0700.

CONTINGENT EXTENSION REQUEST

If this communication is filed after the shortened statutory time period had elapsed and no separate Petition is enclosed, the Commissioner of Patents and Trademarks is petitioned, under 37 C.F.R. §1.136(a), to extend the time for filing a response to the outstanding Office Action by the number of months which will avoid abandonment under 37 C.F.R. §1.135. The fee under 37 C.F.R. § 1.17 should be charged to our Deposit Account No. 15-0700.

AMENDMENTS

 X If checked, amendment(s) to the specification and/or claims are submitted herewith.

1. If checked, an abstract is submitted as the last page of Appendix A.

3. Claims:

Please amend claims 3 and 5 and add new claims 8-10 pursuant to 37 C.F.R. § 1.121(c)(i) as set forth in the “clean” version attached hereto as Appendix A. Entry is respectfully requested. A version with markings to show the changes made pursuant to 37 C.F.R. § 1.121(c)(ii) is attached hereto as Appendix B.

 If checked, the optional complete set of “clean” claims pursuant to 37 C.F.R. § 1.121(c)(3) is attached hereto as Appendix C.

REMARKS/ARGUMENT

This Preliminary Amendment is being submitted to change the multiple dependent claims to single dependent claims in order to reduce the government filing fee.

EXPRESS MAIL CERTIFICATE

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail to Addressee (mail label # EL855846295US) in an envelope addressed to: Asst. Commissioner for Patents, Washington, D.C. 20231, on June 1, 2001:

Dorothy Jenkins


Name of Person Mailing Correspondence


Signature

June 1, 2001

Date of Signature

Respectfully submitted,


Steven I. Weisburd
Registration No.: 27,409
OSTROLENK, FABER, GERB & SOFFEN, LLP
1180 Avenue of the Americas
New York, New York 10036-8403
Telephone: (212) 382-0700

APPENDIX A
“CLEAN” VERSION OF EACH PARAGRAPH/SECTION/CLAIM
37 C.F.R. § 1.121(b)(ii) AND (c)(i)

CLAIMS (with indication of amended or new):

(Amended) 3. A mounting structure of a semiconductor package as set forth in claim 1, wherein a plating is provided on the surface of said pad and an inner surface of said via.

(Amended) 5. A mounting structure of a semiconductor package as set forth in claim 1, wherein said via is projected from said pad in truncated cone shape to extend into a through hole of said printed circuit board and is integrally connected with said connection wiring.

(New) 8. A mounting structure of a semiconductor package as set forth in claim 2, wherein a plating is provided on the surface of said pad and an inner surface of said via.

(New) 9. A mounting structure of a semiconductor package as set forth in claim 2, wherein said via is projected from said pad in truncated cone shape to extend into a through hole of said printed circuit board and is integrally connected with said connection wiring.

(New) 10. A mounting structure of a semiconductor package as set forth in claim 8, wherein said via is projected from said pad in truncated cone shape to extend into a through hole of said printed circuit board and is integrally connected with said connection wiring.

APPENDIX B

VERSION WITH MARKINGS TO SHOW CHANGES MADE

37 C.F.R. § 1.121(b)(iii) AND (c)(ii)

CLAIMS:

3. A mounting structure of a semiconductor package as set forth in claim 1 [or 2], wherein a plating is provided on the surface of said pad and an inner surface of said via.

5. A mounting structure of a semiconductor package as set forth in claim 1 [or 2], wherein said via is projected from said pad in truncated cone shape to extend into a through hole of said printed circuit board and is integrally connected with said connection wiring.

00512591 1